Title (en)

High speed method for plating palladium and palladium alloys

Title (de)

Hochgeschwindigkeitsverfahren zur Plattierung von Palladium und Palladiumlegierungen

Title (fr)

Procédé grande vitesse pour le placage de palladium et d'alliages de palladium

Publication

EP 2017373 A3 20130911 (EN)

Application

EP 08160839 A 20080721

Priority

US 96139307 P 20070720

Abstract (en)

[origin: EP2017373A2] A high speed method of depositing palladium and palladium alloys is disclosed. The high speed method uses an aqueous, ammonia-based bath which has reduced free ammonia in the bath. The high speed method may be used to deposit palladium and palladium alloy coatings on various substrates such as electrical devices and jewelry.

IPC 8 full level

C25D 3/50 (2006.01)

CPC (source: EP US)

C25D 3/50 (2013.01 - EP US); **C25D 3/567** (2013.01 - EP US)

Citation (search report)

- [XY] JP H0711475 A 19950113 - KOJIMA KAGAKU YAKUHIN KK
- [Y] US 4673472 A 19870616 - MORRISSEY RONALD J [US], et al
- [A] US 6251249 B1 20010626 - CHEVALIER JEAN W [US], et al
- [A] WALZ ET AL: "DIE GALVANISCHE ABSCHEIDUNG VON PALLADIUM-NICKEL-LEGIERUNGEN AUS DEM AMMONIAKALISCHEN CHLORIDELEKTROLYTEN", MO METALLOBERFLACHE, IGT INFORMATIONSGESELLSCHAFT TECHNIK, MUNCHEN, DE, vol. 40, no. 3, 1 March 1986 (1986-03-01), pages 112 - 118, XP008163844, ISSN: 0026-0797

Cited by

WO2022129916A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA MK RS

DOCDB simple family (publication)

EP 2017373 A2 20090121; **EP 2017373 A3 20130911**; **EP 2017373 B1 20180926**; CN 101348928 A 20090121; CN 101348928 B 20120704; TW 200923140 A 20090601; TW I391533 B 20130401; US 2009038950 A1 20090212

DOCDB simple family (application)

EP 08160839 A 20080721; CN 200810086859 A 20080317; TW 97126599 A 20080714; US 22003708 A 20080721